



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSC014N04LS	Issued	11. August 2021
MA#	MA001711462		
Package	PG-TDSON-8-17	Weight*	119.19 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.009	0.85	0.85	8469	8469
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	iron	7439-89-6	0.038	0.03		317	
	non noble metal	copper	7440-50-8	37.762	31.68	31.72	316824	317236
wire	noble metal	gold	7440-57-5	0.045	0.04	0.04	374	374
encapsulation	organic material	carbon black	1333-86-4	0.132	0.11		1108	
	plastics	epoxy resin	-	5.150	4.32		43207	
	inorganic material	silicondioxide	60676-86-0	38.733	32.51	36.94	324975	369290
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12179	12179
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1389	1389
solder	non noble metal	tin	7440-31-5	0.029	0.02		244	
	noble metal	silver	7440-22-4	0.036	0.03		305	
	non noble metal	lead	7439-92-1	1.387	1.16	1.21	11636	12185
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			28	
	non noble metal	zinc	7440-66-6	0.013	0.01		113	
	non noble metal	iron	7439-89-6	0.269	0.23		2254	
	non noble metal	copper	7440-50-8	10.909	9.15	9.39	91528	93923
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		55	
	non noble metal	zinc	7440-66-6	0.026	0.02		222	
	non noble metal	iron	7439-89-6	0.529	0.44		4439	
	non noble metal	copper	7440-50-8	21.482	18.02	18.49	180239	184955
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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